# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**

- HP Pavilion 14 Notebook PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>3</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing refractory ceramic fibers | 0
Components, parts and materials containing radioactive substances | 0

2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>Screwdriver #1</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove battery module
2. Dis-fasten Base Door screw*1
3. Disassemble Service Door
4. Pull out wire cable connectors*2 (HDD, ODD)
5. Dis-fasten HDD screw*2
6. Remove HDD
7. Dis-fasten WLAN screw*1
8. Dis-fasten keyboard screw*3
9. Pull out keyboard membrane
10. Remove keyboard
11. Dis-fasten ODD screw*1
12. Remove ODD
13. Dis-fasten BASE screw*15
14. Dis-fasten KB Deck screw*4
15. Pull out FFC*2 (Power, Touchpad)
16. Disassemble KB Deck
17. Pull out FFC*1 (USB)
18. Dis-fasten daughter boards screw*3 (Power, USB)
19. Remove daughter boards*3 (Power, TP Button, USB)
20. Pull out wire cable connectors*2 (LCD, DC cable)
21. Dis-fasten motherboard screw*1
22. Dis-fasten speaker screw*2
23. Pull out wire cable*1 (speaker)
24. Remove speaker -L & -R
25. Remove motherboard
26. Pull out fan cable
27. Dis-fasten Fan screws*1
28. Remove Fan module
29. Dis-fasten thermal module screw*7
30. Remove thermal module
31. Remove DC cable
32. Remove ODD cable
33. Dis-fasten Hinge screw*6

PSG instructions for this template are available at EL-MF877-01
34. Remove LCD module  
35. Dis-fasten LCD Bezel screws*2  
36. Remove LCD bezel  
37. Dis-fasten Hinge BKT screw*6  
38. Pull out LCD cable & camera cable  
39. Dis-fasten LCD BKT -L & -R screws*4  
40. Remove LCD module  
41. Remove Camera module  
42. Remove Antenna cables -L & -R  

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).  

3.21 Total part disassembly  
3.22 Remove battery module  
3.23 Remove service door  
3.24 LCD module set disassembly  
3.25 Top case disassembly  
3.26 Thermal module and mother board disassembly  
3.27 Bottom case disassembly